DFX Guidelines

Developed by the DFX Standards Subcommittee (1-14) of the Printed Board Design Committee (1-10) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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IPC
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DFX Guidelines

1 SCOPE
This document provides guidelines for establishing a best practice methodology for use in developing a formal DFX (Design for Manufacturing, Fabrication, Assembly, Testability, Cost, Reliability, Environment, Reuse) process for layout of printed board assemblies that utilize surface mount and through hole devices.

1.1 Purpose The document provides a DFX process framework to establish a discipline of design review necessary to perform a detailed analysis of manufacturability attributes commonly found in electronics hardware for fabrication and around which to model a printed board assembly.

1.2 Goals of This Document The goals of this document are to:
• Use a multi-discipline engineering assessment tactic on elements influencing DFX.
• Allow the user to establish standardized DFX checklist(s) for major design elements such as bare printed board fabrication, printed board assembly manufacturing, electrical testability, and elements influencing product reliability, reuse, and impact on environment.

1.3 Limitations of This Document Electronics hardware defined under this DFX review process is limited to features of influence on DFX for bare printed board and printed board assembly.

2 APPLICABLE DOCUMENTS

2.1 IPC1
J-STD-001 Requirements for Soldered Electrical and Electronic Assemblies
IPC-T-50 Terms and Definitions for Interconnecting and Packaging Electronic Circuits
IPC-CH-65 Guidelines for Cleaning of Printed Boards and Assemblies
IPC-D-279 Design Guidelines for Reliable Surface Mount Technology Printed Board Assemblies
IPC-D-325 Documentation Requirements for Printed Boards, Assemblies and Support Drawings
IPC-A-610 Acceptability of Electronic Assemblies
IPC-SM-785 Guidelines for Accelerated Reliability Test of Surface Mount Solder Attachments
IPC-CC-830 Qualification and Performance of Electrical Insulating Compound for Printed Wiring Assemblies
IPC-2221 Generic Standard on Printed Board Design
IPC-2222 Sectional Design Standard for Rigid Organic Printed Boards
IPC-2223 Sectional Design Standard for Flexible Printed Boards
IPC-2224 Sectional Standard for Design of PWBs for PC Cards
IPC-2225 Sectional Design Standard for Organic Multichip Modules (MCM-L) and MCM-L Assemblies
IPC-2226 Sectional Design Standard for High Density Interconnect (HDI) Printed Boards
IPC-2581 Generic Requirements for Printed Board Assembly Products Manufacturing Description Data and Transfer Methodology
IPC-2615 Printed Board Dimensions and Tolerances
IPC-4761 Design Guide for Protection of Printed Board Via Structures

1. www.ipc.org